#### **PATENT**

Town age	$\frac{1}{2}$ IN THE UNITED STATES PAT	ENT AND	TRADEMARK O	FFICE
AMETE I	he application of: Singh et al.	) ) )	Group Art Unit:	Unassigned
• •	cation No. 10/633,004 7/31/2003	)	Examiner: Unas Atty. Docket No	
For:	PAD OVER ACTIVE CIRCUIT SYSTEM AND METHOD WITH MESHED SUPPORT STRUCTURE	) ) ) )	Date: November	er 6, 2003

### **CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450 on November 6, 2093.

Signed:

Erica L. Farlow

# INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR §§1.56 AND 1.97(b)

Commissioner of Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449, copies of which are attached, may be material to examination of the above-identified patent application. Applicants submit these references in compliance with their duty of disclosure pursuant to 37 CFR §§ 1.56 and 1.97. The Examiner is requested to make these references of official record in this application.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that these references indeed constitute prior art.

This Information Disclosure Statement is believed to be filed before the mailing date of a first Office Action on the merits. Accordingly, it is believed that no fees are due in connection with the filing of this Information Disclosure Statement. However, if it is determined that any fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 50-1351 (Order No. NVIDP234/P000825).

Respectfully submitted,

Silicon Vatley IP Group, PC

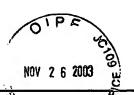
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Information Disclosure
Statement By Applicant

(Use Several Sheets if Necessary)

Atty. Docket No.

NVIDP234/P000825

Applicant: Singh et al.

Filing Date: 7/31/2003

Application No.:

10/633,004

Group Art Unit: Unassigned

# **U.S. Patent Documents**

Examiner						Sub-	Filing
Initial	No.	Patent No.	Date	Patentee	Class	class	Date
	A	6,538,326	03/25/2003	Shimizu et al.	257	758	10/4/2001
	В	6,552,438	04/22/2003	Lee et al.	257	784	12/21/2000
	С	5,965,903	10/12/1999	Chittipeddi et al.	257	48	02/12/1998
	D	6,297,562	10/02/2001	Tilly	257	780	09/20/1999
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	F	6,365,970	04/02/2002	Tsai et al.	257	751	12/10/1999
	G	6,417,087	07/09/2002	Chittipeddi et al.	438	612	12/16/1999
	Н	4,636,832	01/13/1987	Abe et al.	357	68	03/04/1986
	I	4,723,197	02/02/1988	Takiar et al.	361	403	12/16/1985
	J	6,100,589	08/08/2000	Tanaka	257	758	08/19/1997
	K	4,984,061	01/08/1991	Matsumoto	357	68	05/10/1988
	L	6,384,486	05/07/2002	Zuniga et al.	257	781	12/10/1999
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	T	6,144,100	11/07/2000	Shen et al.	257	762	10/28/1997
	U	5,751,065	05/12/1998	Chittipeddi et al.	257	758	10/30/1995

## Other Documents

Examiner				
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	V	Heinen, Gail et al., "Wire Bonds Over Active Circuits", 1994, IEEE		
.1.	W	Chou, Kuo-Yu et al., "Active Circuits Under Wire Bonding I/O Pads in 0.13 µm Eight-		
	Level Cu Metal, FSG Low-K Inter-Metal Dielectric CMOS Technology +", October			
·		2001, IEEE		
X Efland, T., et al., "LeadFrameOnChip offers Integrated Power Bus and Boy Active Circuit" 2001 International Symposium on Power Semiconductor.				
<i>\</i>	Active Circuit", 2001, International Symposium on Power Semiconductor Device			
ICs, Osaka				
Examiner		Date Considered		

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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Form 1449 (Modified)

**Information Disclosure Statement By Applicant** 

(Use Several Sheets if Necessary)

Atty. Docket No.

NVIDP234/P000825

Applicant: Singh et al.

Filing Date: 7/31/2003

Application No.:

10/633,004

Group Art Unit: Unassigned

## **U.S.** Patent Documents

Examiner						Sub-	Filing
Initial	No.	Patent No.	Date	Patentee	Class	class	Date
	Y	6,448,641	09/10/2002	Ker et al.	257	700	06/09/1999
	Z	6,486,051	11/26/2002	Sabin et al.	438	612	03/17/1999
	AA	6,489,688	12/03/2002	Baumann et al.	257	786	05/02/2001
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	GG						
	HH						
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	KK						
	LL						
	MM						
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	00						-
	PP						
	QQ						
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# **Other Documents**

Examiner						
Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication				
	TT	Saran, Mukul et al., "Elimination of Bond-pad Damage Through Structural Reinforcement of Intermetal Dielectrics", 1998, IEEE 36th Annual International Reliability Physics Symposium, Reno, Nevada				
Examiner		Date Considered				

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.